

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.32046	100.0	23.6
Subtotal				0.32046	100	23.6
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01978	0.03	1.4568
	Copper alloy	Iron (Fe)	7439-89-6	0.06594	0.1	4.856
	Copper alloy	Copper (Cu)	7440-50-8	65.85322	99.87	4,849.6872
Subtotal				65.93894	100	NaN
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.31987	4.0	97.2
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	4.94949	15.0	364.5
	Filler	Silica fused	60676-86-0	24.41751	74.0	1,798.2
	Flame retardant	Metal hydroxide		2.30976	7.0	170.1
Subtotal				32.99663	100	NaN
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.40737	100.0	30
Subtotal				0.40737	100	30
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.00166	100.0	0.12231
Subtotal				0.00166	100	0.12231
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.13089	65.0	9.63934
	Lead alloy	Silver (Ag)	7440-22-4	0.05034	25.0	3.70744
	Lead alloy	Antimony (Sb)	7440-36-0	0.02014	10.0	1.48298
Subtotal				0.20137	100	14.82976
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.13357	100.0	9.83664
Subtotal				0.13357	100	9.83664
Total				100	100	NaN

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